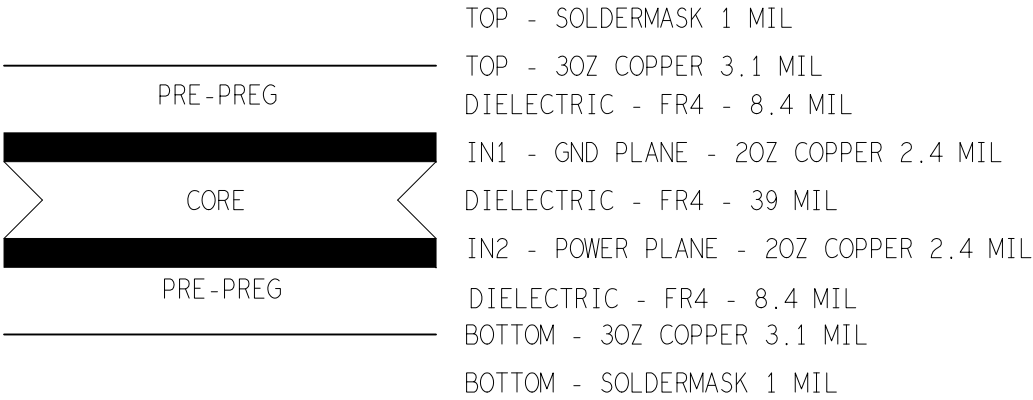


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	+3.0/-3.0	PLATED	145
▪	12.0	+3.0/-3.0	PLATED	42
•	12.0	+3.0/-3.0	PLATED	1063
◦	40.0	+3.0/-3.0	PLATED	81
◉	55.0	+3.0/-3.0	PLATED	4
◊	72.0	+3.0/-3.0	PLATED	20
△	110.0	+2.0/-2.0	PLATED	4
◯	118.0	+2.0/-2.0	PLATED	2
◯	126.0	+2.0/-2.0	NON-PLATED	2
◻	152.0	+2.0/-2.0	NON-PLATED	1
◯	156.0	+2.0/-2.0	NON-PLATED	5

FABRICATION NOTES:

- 1.) MATERIAL SELECTION:  
PER LATEST REVISION OF IPC-4101 (OR EQUIVALENT) UL RECOGNIZED ZPMV2 MIN.  
130C FLAME CLASS V-0 OR BETTER. .062+/- .007 MATERIAL PER IPC-4101.  
3 OZ. COPPER FOR EXTERNAL LAYERS. 2 OZ. COPPER FOR INTERNAL LAYERS.  
SOLDERABLE SURFACES TO BE SILVER IMMERSION FINISH.
- 2.) SOLDER RESIST: THE USE OF SOLDER RESIST COATING SHALL BE IN  
ACCORDANCE WITH THE REQUIREMENTS OF IPC-SM-840. ALL SOLDERABLE SURFACES  
ARE TO BE FREE OF SOLDER RESIST. COLOR - GREEN.  
USE LIQUID PHOTOIMAGEABLE RESIST.
- 3.) SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. ALL COMPONENT AND TESTPOINT  
LANDS ARE TO BE FREE OF INK.
- 4.) MANUFACTURER'S IDENTIFICATION: ADD IN ETCH OR TO SILKSCREEN.
- 5.) ELECTRICAL BARE BOARD TEST REQUIRED.
- 6.) DRILL SIZES ARE FINISHED SIZE AFTER PLATING.
- 7.) FABRICATE TO MEET EU ROHS DIRECTIVE.
- 8.) PCB MUST HAVE UL 94V-0 AND CTI RATING MARKED ON ONE SIDE.
- 9.) MAX WARP AND TWIST NOT TO EXCEED 0.010 PER LINEAR INCH.
- 10.) MIN ANNULAR RING: 0.003. MIN PLATED HOLE WALL THICKNESS 0.001.
- 11.) DIMENSIONAL TOL: XX +/- 0.010. XXX +/- 0.005.
- 12.) FABRICATE IN ACCORDANCE WITH IPC-600 OR IPC-6012 LATEST REVISION. CLASS 2.
- 13.) COPPER THEIVING OF THE SIGNAL LAYERS IS ALLOWED. SPACING TO ANY EXISTING  
BOARD FEATURE TO BE 0.060 MINIMUM.



NOMINAL REQUIRED THICKNESS 0.062 +/- 0.007

